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Kind regards,

Team Nexperia

74AHC573; 74AHCT573

Octal D-type transparent latch; 3-state

Rev. 7 — 8 November 2011

Product data sheet

1. General description

The 74AHC573; 74AHCT573 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL). It is specified in compliance with JEDEC standard No. 7A.

The 74AHC573; 74AHCT573 consists of eight D-type transparent latches featuring separate D-type inputs for each latch and 3-state true outputs for bus oriented applications. A latch enable input (LE) and an output enable input ($\overline{OE}$) are common to all latches.

When pin LE is HIGH, data at the Dn inputs enters the latches. In this condition the latches are transparent, i.e. a latch output will change state each time its corresponding Dn input changes. When pin LE is LOW, the latches store the information that is present at the Dn inputs, after a set-up time preceding the HIGH-to-LOW transition of LE.

When pin $\overline{OE}$ is LOW, the contents of the 8 latches are available at the outputs. When pin $\overline{OE}$ is HIGH, the outputs go to the high-impedance OFF-state. Operation of the $\overline{OE}$ input does not affect the state of the latches.

The 74AHC573; 74AHCT573 is functionally identical to the 74AHC373; 74AHCT373, but has a different pin arrangement.

2. Features and benefits

- Balanced propagation delays
- All inputs have a Schmitt trigger action
- Common 3-state output enable input
- Functionally identical to the 74AHC373; 74AHCT373
- Inputs accept voltages higher than V_{CC}
- Input levels:
 - ◆ For 74AHC573: CMOS input level
 - ◆ For 74AHCT573: TTL input level
- ESD protection:
 - ◆ HBM EIA/JESD22-A114E exceeds 2000 V
 - ◆ MM EIA/JESD22-A115-A exceeds 200 V
 - ◆ CDM EIA/JESD22-C101C exceeds 1000 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$



3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AHC573				
74AHC573D	−40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74AHC573PW	−40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74AHC573BQ	−40 °C to +125 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1
74AHCT573				
74AHCT573D	−40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74AHCT573PW	−40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74AHCT573BQ	−40 °C to +125 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1

4. Functional diagram

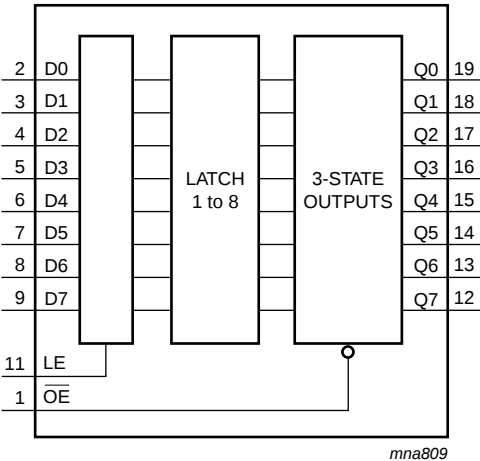
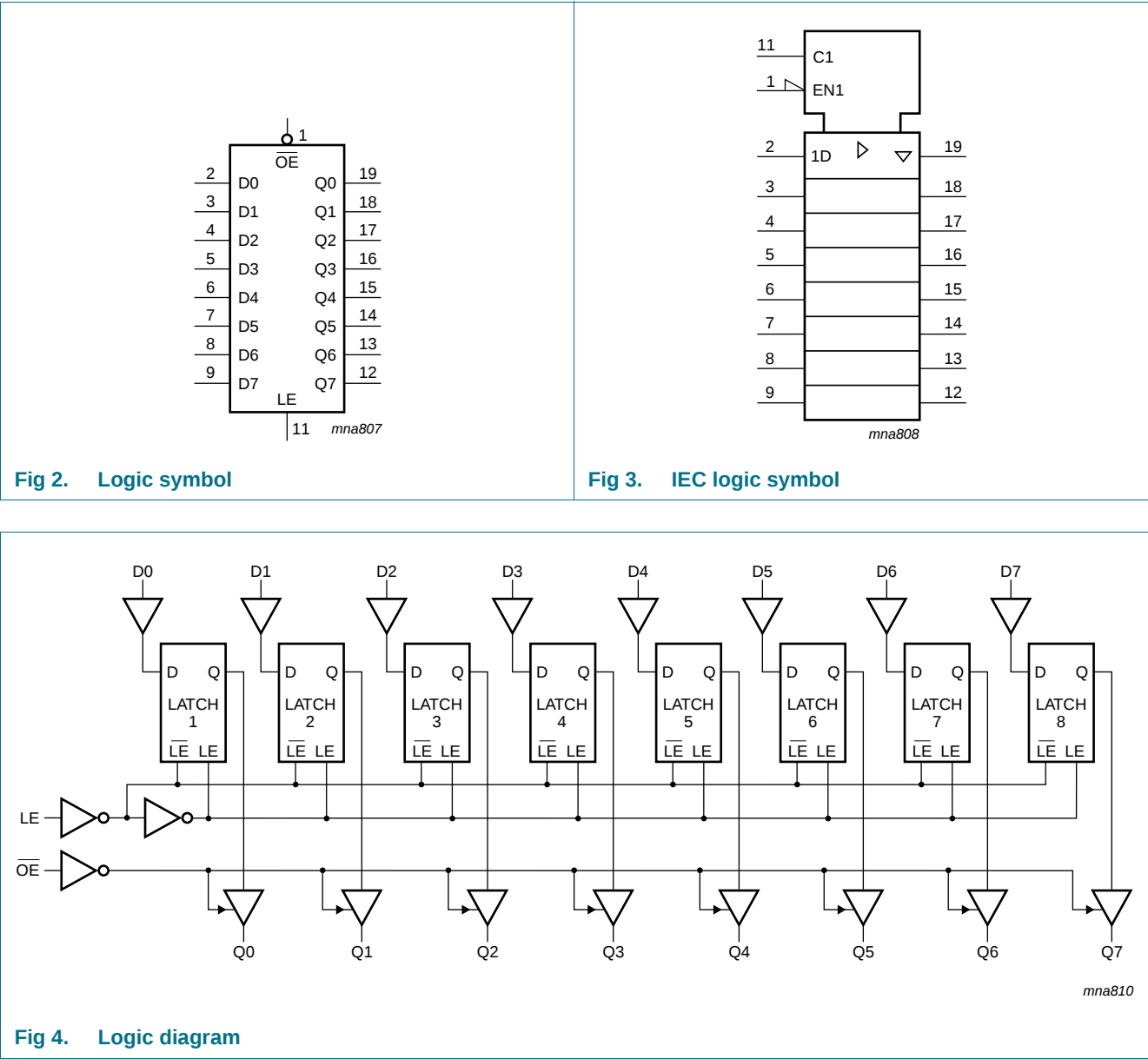
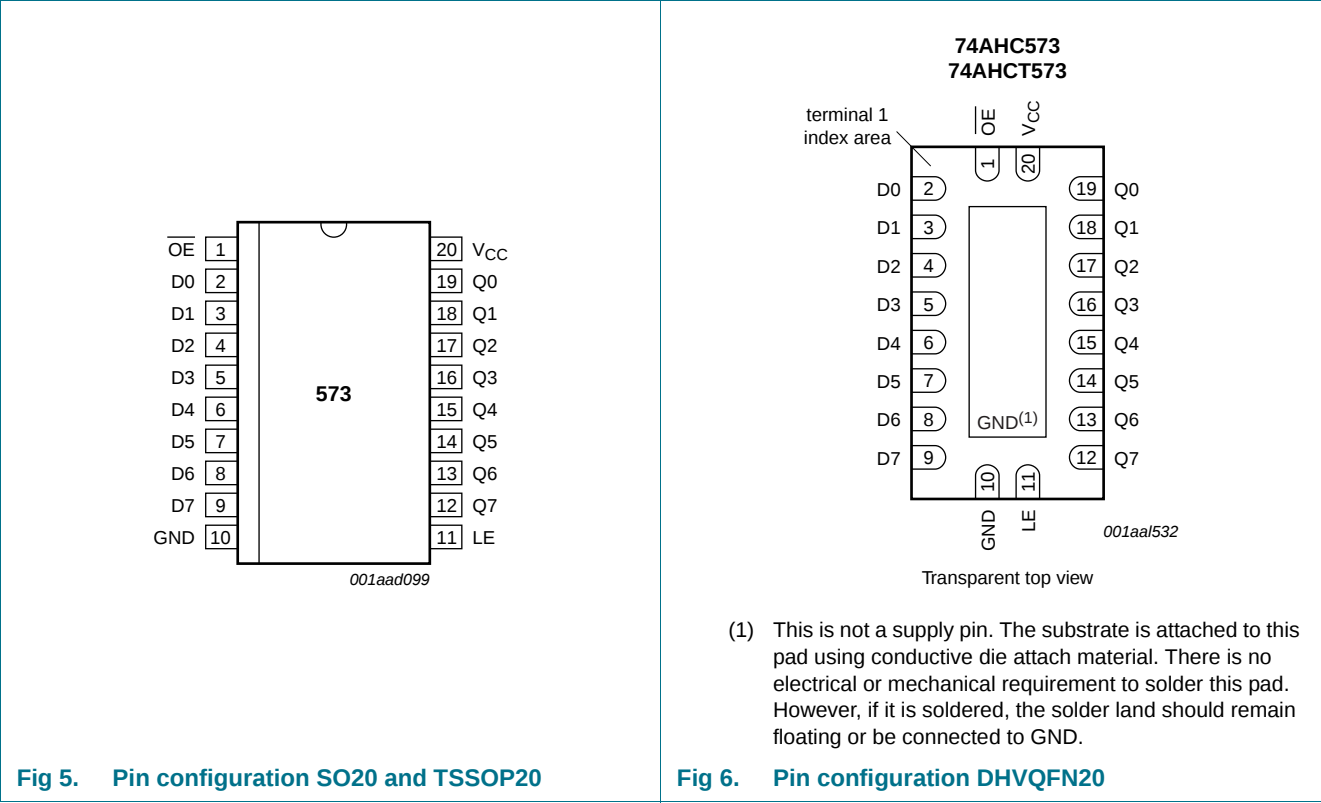


Fig 1. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{\text{OE}}$	1	output enable input (active LOW)
D0 to D7	2, 3, 4, 5, 6, 7, 8, 9	data input
GND	10	ground (0 V)
LE	11	latch enable (active HIGH)
Q0 to Q7	19, 18, 17, 16, 15, 14, 13, 12	data output
V _{CC}	20	supply voltage

6. Functional description

Table 3. Function table^[1]

Operating mode	Input			Internal latch	Output Qn
	OE	LE	Dn		
Enable and read register (transparent mode)	L	H	L	L	L
			H	H	H
Latch and read register	L	L	l	L	L
			h	H	H
Latch register and disable outputs	H	L	l	L	Z
			h	H	Z

- [1] H = HIGH voltage level;
 h = HIGH voltage level one set-up time prior to the HIGH-to-LOW LE transition;
 L = LOW voltage level;
 l = LOW voltage level one set-up time prior to the HIGH-to-LOW LE transition;
 Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		−0.5	+7.0	V
V _I	input voltage		−0.5	+7.0	V
I _{IK}	input clamping current	V _I < −0.5 V	^[1] −20	-	mA
I _{OK}	output clamping current	V _O < −0.5 V or V _O > V _{CC} + 0.5 V	^[1] −20	+20	mA
I _O	output current	V _O = −0.5 V to (V _{CC} + 0.5 V)	−25	+25	mA
I _{CC}	supply current		-	+75	mA
I _{GND}	ground current		−75	-	mA
T _{stg}	storage temperature		−65	+150	°C
P _{tot}	total power dissipation	T _{amb} = −40 °C to +125 °C	^[2] -	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO20 packages: above 70 °C the value of P_{tot} derates linearly at 8 mW/K.
 For TSSOP20 packages: above 60 °C the value of P_{tot} derates linearly at 5.5 mW/K.
 For DHVQFN20 packages: above 60 °C the value of P_{tot} derates linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
74AHC573						
V_{CC}	supply voltage		2.0	5.0	5.5	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	-	-	100	ns/V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	20	ns/V
74AHCT573						
V_{CC}	supply voltage		4.5	5.0	5.5	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	20	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C			Unit
			Min	Typ	Max	Min	Max	Min	Typ	Max	
74AHC573											
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	-	-	1.5	-	1.5	-	-	V
		V _{CC} = 3.0 V	2.1	-	-	2.1	-	2.1	-	-	V
		V _{CC} = 5.5 V	3.85	-	-	3.85	-	3.85	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	-	0.5	-	0.5	-	-	0.5	V
		V _{CC} = 3.0 V	-	-	0.9	-	0.9	-	-	0.9	V
		V _{CC} = 5.5 V	-	-	1.65	-	1.65	-	-	1.65	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}									
		I _O = −50 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	-	V
		I _O = −50 μA; V _{CC} = 3.0 V	2.9	3.0	-	2.9	-	2.9	-	-	V
		I _O = −50 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	-	V
		I _O = −4.0 mA; V _{CC} = 3.0 V	2.58	-	-	2.48	-	2.40	-	-	V
		I _O = −8.0 mA; V _{CC} = 4.5 V	3.94	-	-	3.80	-	3.70	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}									
		I _O = 50 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	-	0.1	V
		I _O = 50 μA; V _{CC} = 3.0 V	-	0	0.1	-	0.1	-	-	0.1	V
		I _O = 50 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	-	0.1	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.36	-	0.44	-	-	0.55	V
		I _O = 8.0 mA; V _{CC} = 4.5 V	-	-	0.36	-	0.44	-	-	0.55	V

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C			Unit
			Min	Typ	Max	Min	Max	Min	Typ	Max	
I _{OZ}	OFF-state output current	V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; V _{CC} = 5.5 V	-	-	±0.25	-	±2.5	-	-	±10.0	µA
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	-	2.0	µA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	4.0	-	40	-	-	80	µA
C _I	input capacitance	V _I = V _{CC} or GND	-	3	10	-	10	-	-	10	pF
C _O	output capacitance		-	4	-	-	-	-	-	10	pF

74AHCT573

V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	-	-	2.0	-	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	-	0.8	-	0.8	-	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V									
		I _O = –50 µA	4.4	4.5	-	4.4	-	4.4	-	-	V
		I _O = –8.0 mA	3.94	-	-	3.80	-	3.70	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V									
		I _O = 50 µA	-	0	0.1	-	0.1	-	-	0.1	V
		I _O = 8.0 mA	-	-	0.36	-	0.44	-	-	0.55	V
I _{OZ}	OFF-state output current	V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND per input pin; other inputs at V _{CC} or GND; I _O = 0 A	-	-	±0.25	-	±2.5	-	-	±10.0	µA
I _I	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	-	2.0	µA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	4.0	-	40	-	-	80	µA
ΔI _{CC}	additional supply current	per input pin; V _I = V _{CC} – 2.1 V; I _O = 0 A; other pins at V _{CC} or GND; V _{CC} = 4.5 V to 5.5 V	-	-	1.35	-	1.5	-	-	1.5	mA
C _I	input capacitance	V _I = V _{CC} or GND	-	3	10	-	10	-	-	10	pF
C _O	output capacitance		-	4	-	-	-	-	-	10	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 11](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	Min	Max	
74AHC573										
t _{pd}	propagation delay	Dn to Qn; see Figure 7								
		V _{CC} = 3.0 V to 3.6 V								
		C _L = 15 pF	-	5.5	11.0	1.0	13.0	1.0	14.0	ns
		C _L = 50 pF	-	7.8	14.5	1.0	16.5	1.0	18.5	ns
		V _{CC} = 4.5 V to 5.5 V								
		C _L = 15 pF	-	3.9	6.8	1.0	8.0	1.0	8.5	ns
		C _L = 50 pF	-	5.5	8.8	1.0	10.0	1.0	11.0	ns
		LE to Qn; see Figure 8								
		V _{CC} = 3.0 V to 3.6 V								
		C _L = 15 pF	-	5.8	11.9	1.0	14.0	1.0	15.0	ns
		C _L = 50 pF	-	8.3	15.4	1.0	17.5	1.0	19.5	ns
		V _{CC} = 4.5 V to 5.5 V								
C _L = 15 pF	-	4.2	7.7	1.0	9.0	1.0	10.0	ns		
C _L = 50 pF	-	5.9	9.7	1.0	11.0	1.0	12.5	ns		
t _{en}	enable time	OE to Qn; see Figure 9								
		V _{CC} = 3.0 V to 3.6 V								
		C _L = 15 pF	-	5.8	11.5	1.0	13.5	1.0	14.5	ns
		C _L = 50 pF	-	8.3	15.0	1.0	17.0	1.0	19.0	ns
		V _{CC} = 4.5 V to 5.5 V								
		C _L = 15 pF	-	4.4	7.7	1.0	9.0	1.0	10.0	ns
C _L = 50 pF	-	6.3	9.7	1.0	11.0	1.0	12.5	ns		
t _{dis}	disable time	OE to Qn; see Figure 9								
		V _{CC} = 3.0 V to 3.6 V								
		C _L = 15 pF	-	6.8	11.0	1.0	13.0	1.0	14.0	ns
		C _L = 50 pF	-	9.7	14.5	1.0	16.5	1.0	18.5	ns
		V _{CC} = 4.5 V to 5.5 V								
		C _L = 15 pF	-	4.6	7.7	1.0	9.0	1.0	10.0	ns
C _L = 50 pF	-	7.4	9.7	1.0	11.0	1.0	12.5	ns		
t _W	pulse width	LE HIGH; see Figure 8								
		V _{CC} = 3.0 V to 3.6 V	5.0	-	-	5.0	-	5.0	-	ns
		V _{CC} = 4.5 V to 5.5 V	5.0	-	-	5.0	-	5.0	-	ns
t _{su}	set-up time	Dn to LE; see Figure 10								
		V _{CC} = 3.0 V to 3.6 V	3.5	-	-	3.5	-	3.5	-	ns
		V _{CC} = 4.5 V to 5.5 V	3.5	-	-	3.5	-	3.5	-	ns

Table 7. Dynamic characteristics ...continuedVoltages are referenced to GND (ground = 0 V); for test circuit see [Figure 11](#).

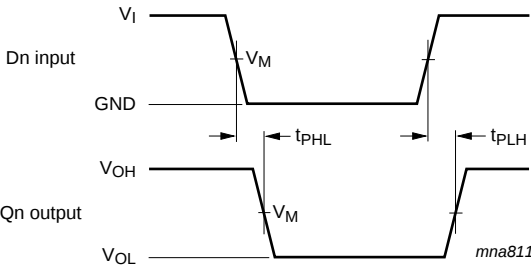
Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	Min	Max	
t _h	hold time	Dn to LE; see Figure 10								
		V _{CC} = 3.0 V to 3.6 V	1.5	-	-	1.5	-	1.5	-	ns
		V _{CC} = 4.5 V to 5.5 V	1.5	-	-	1.5	-	1.5	-	ns
C _{PD}	power dissipation capacitance	f _i = 1 MHz; V _i = GND to V _{CC}	^[5] -	12	-	-	-	-	-	pF
74AHCT573; V_{CC} = 4.5 V to 5.5 V										
t _{pd}	propagation delay	Dn to Qn; see Figure 7	^[2]							
		C _L = 15 pF	-	3.5	5.5	1	6.5	1	7.0	ns
		C _L = 50 pF	-	4.9	7.5	1	8.5	1	9.5	ns
		LE to Qn; see Figure 8	^[2]							
		C _L = 15 pF	-	3.9	6.0	1	7.0	1	7.5	ns
t _{en}	enable time	OE to Qn; see Figure 9	^[3]							
		C _L = 15 pF	-	4.1	6.5	1	7.5	1	8.5	ns
		C _L = 50 pF	-	5.9	8.5	1	10.0	1	11.0	ns
t _{dis}	disable time	OE to Qn; see Figure 9	^[4]							
		C _L = 15 pF	-	4.5	6.5	1	7.5	1	8.5	ns
		C _L = 50 pF	-	6.4	9.0	1	10.0	1	11.5	ns
t _W	pulse width	LE HIGH; see Figure 8	5.0	-	-	5.0	-	5.0	-	ns
t _{su}	set-up time	Dn to LE; see Figure 10	3.5	-	-	3.5	-	3.5	-	ns
t _h	hold time	Dn to LE; see Figure 10	1.5	-	-	1.5	-	1.5	-	ns
C _{PD}	power dissipation capacitance	f _i = 1 MHz; V _i = GND to V _{CC}	^[5] -	18	-	-	-	-	-	pF

[1] Typical values are measured at nominal supply voltage (V_{CC} = 3.3 V and V_{CC} = 5.0 V).[2] t_{pd} is the same as t_{pHL} and t_{pLH}.[3] t_{en} is the same as t_{pZH} and t_{pZL}.[4] t_{dis} is the same as t_{pHZ} and t_{pLZ}.[5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$$
 where:
f_i = input frequency in MHz;f_o = output frequency in MHz;C_L = output load capacitance in pF;V_{CC} = supply voltage in V;

N = number of inputs switching;

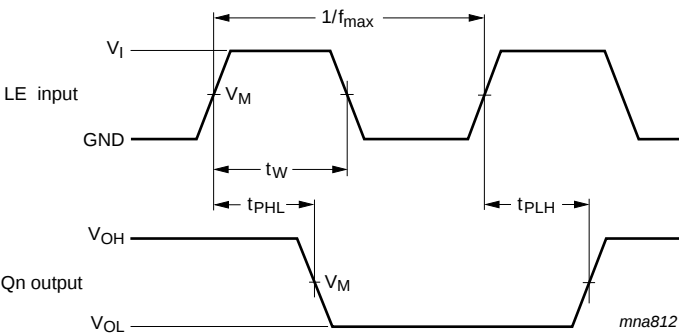
Σ(C_L × V_{CC}² × f_o) = sum of the outputs.

11. Waveforms



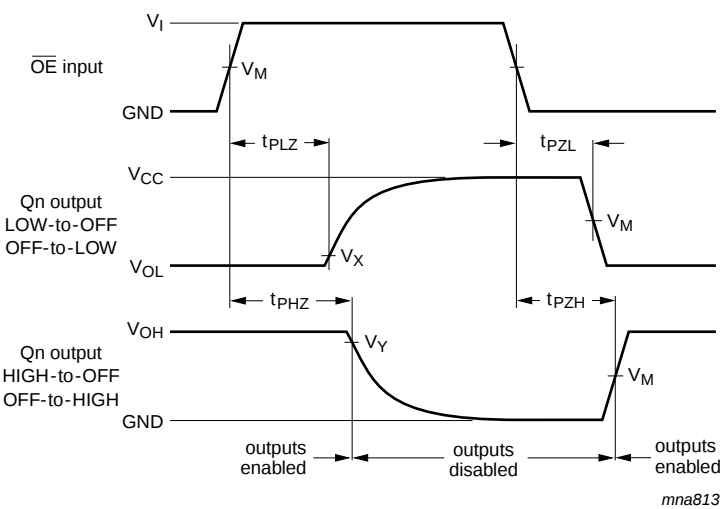
Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 7. Data input to output propagation delays



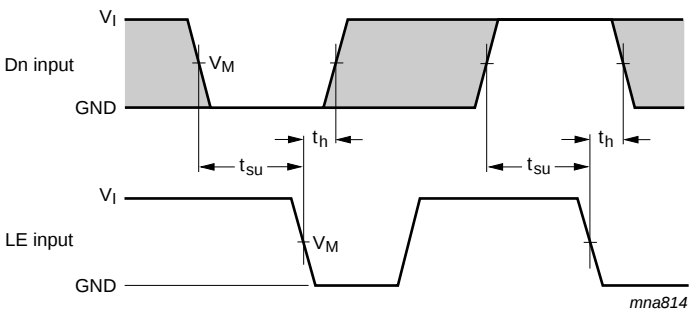
V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 8. Latch enable input to output propagation delays



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 9. Enable and disable times



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.
The shaded areas indicate when the input is permitted to change for predictable output performance.

Fig 10. Data set-up and hold times

Table 8. Measurement points

Type	Input	Output		
	V_M	V_M	V_X	V_Y
74AHC573	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$
74AHCT573	1.5 V	$0.5 \times V_{CC}$	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$

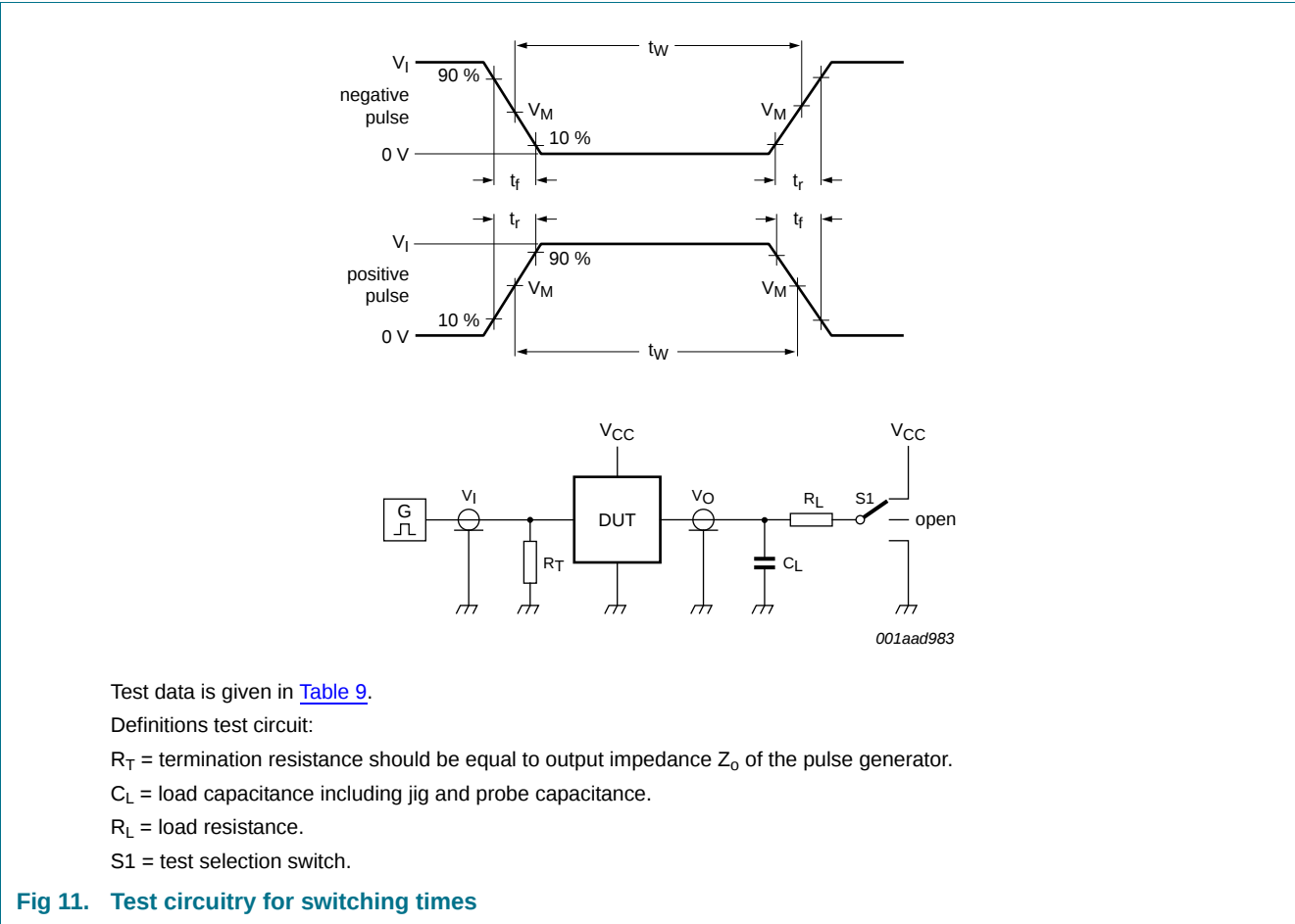


Fig 11. Test circuitry for switching times

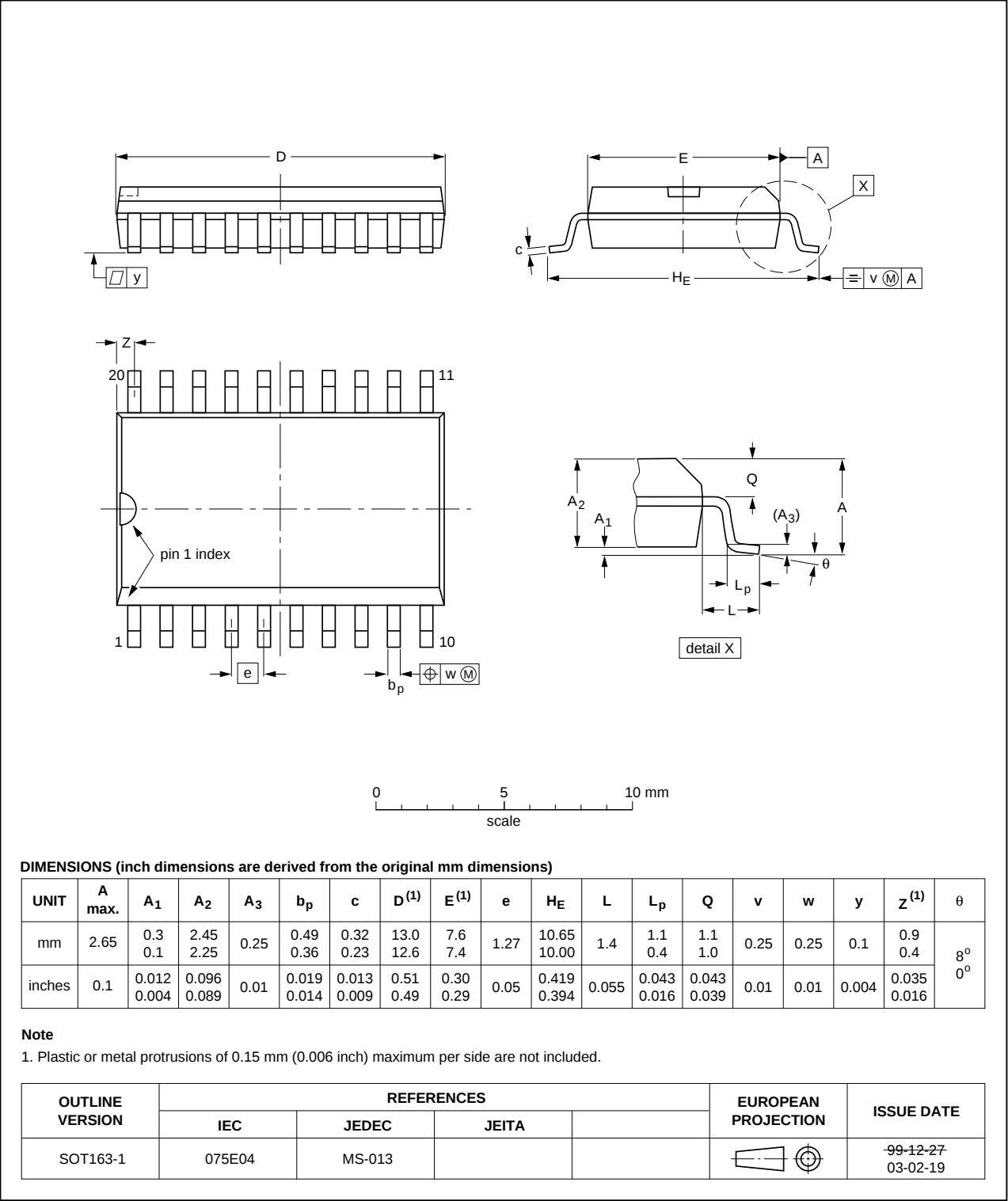
Table 9. Test data

Type	Input		Load		S1 position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74AHC573	V_{CC}	$\leq 3.0 \text{ ns}$	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}
74AHCT573	3.0 V	$\leq 3.0 \text{ ns}$	15 pF, 50 pF	1 k Ω	open	GND	V_{CC}

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



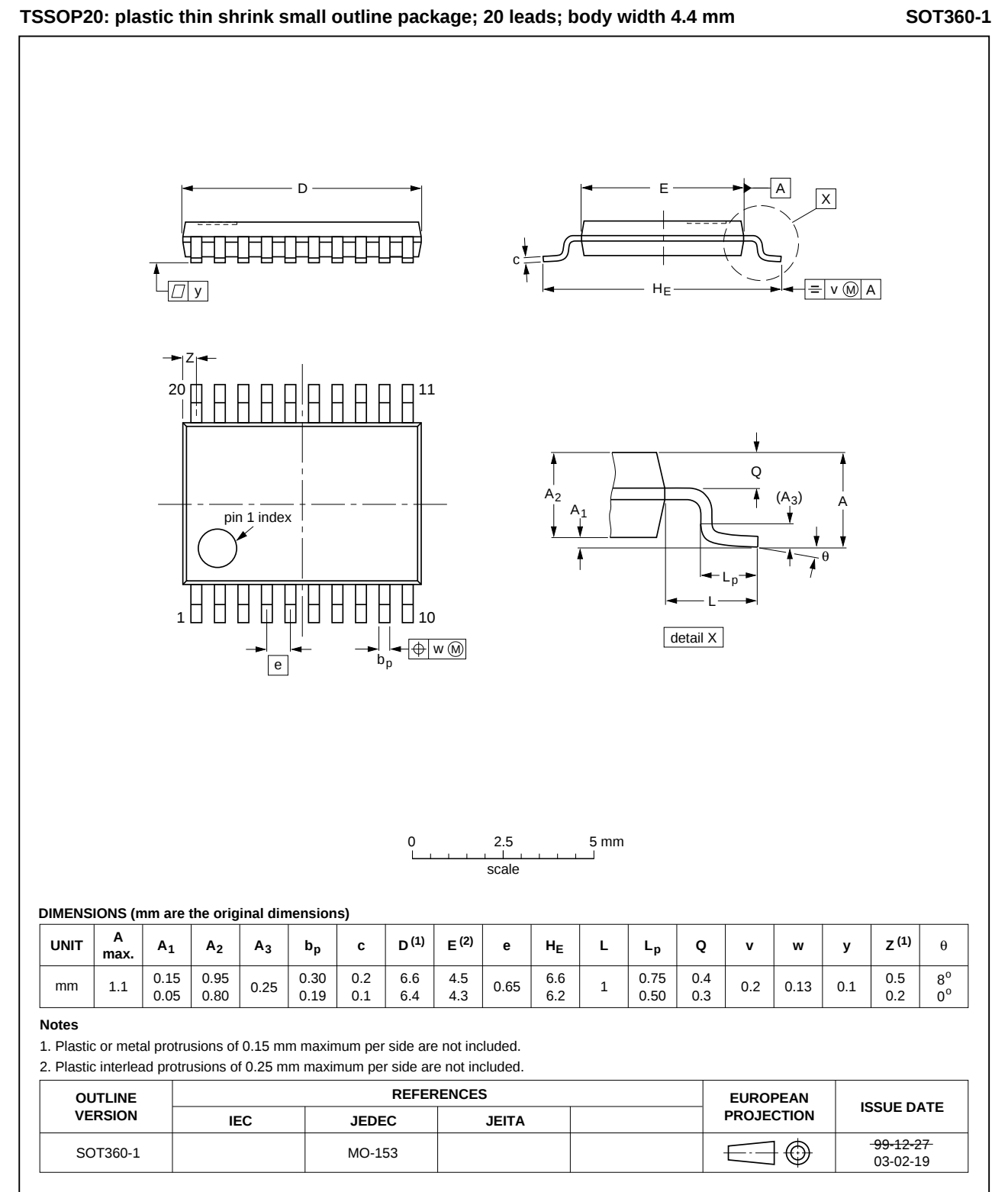


Fig 13. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

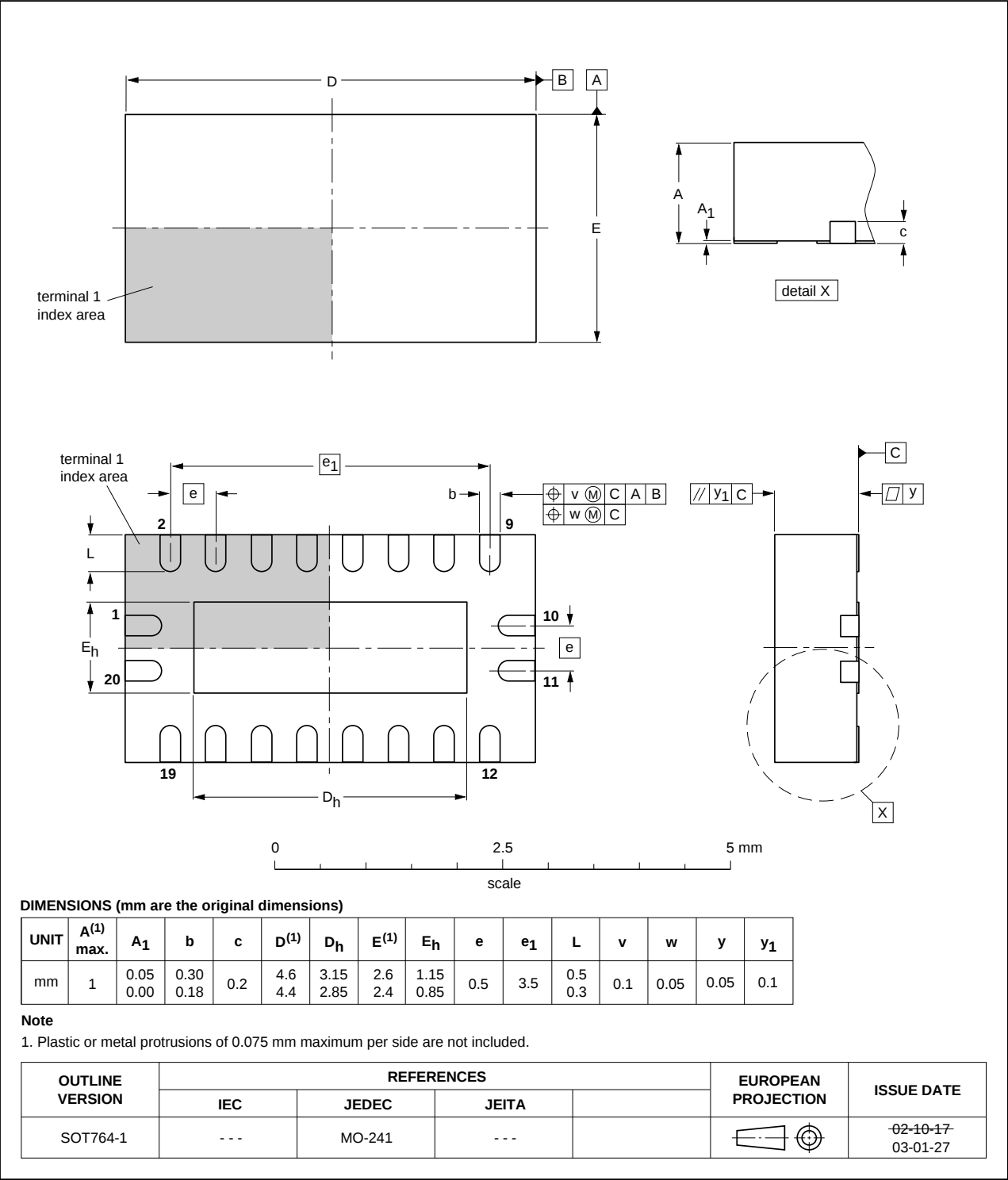


Fig 14. Package outline SOT764-1 (DHVQFN20)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT573 v.7	20111108	Product data sheet	-	74AHC_AHCT573 v.6
Modifications:	• Legal pages updated.			
74AHC_AHCT573 v.6	20101125	Product data sheet	-	74AHC_AHCT573 v.5
74AHC_AHCT573 v.5	20100325	Product data sheet	-	74AHC_AHCT573 v.4
74AHC_AHCT573 v.4	20100303	Product data sheet	-	74AHC_AHCT573 v.3
74AHC_AHCT573 v.3	20080424	Product data sheet	-	74AHC_AHCT573 v.2
74AHC_AHCT573 v.2	20031208	Product specification	-	74AHC_AHCT573 v.1
74AHC_AHCT573 v.1	19990927	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Date of release: 8 November 2011

Document identifier: 74AHC_AHCT573